

L Number	Hits	Search Text	DB	Time stamp
1	2	"20020192944"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 18:24
2	30369	(measur\$5 calculat\$4) near15 stress	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 19:22
3	740	((measur\$5 calculat\$4) near15 stress) near12 (cu copper metal metallization wiring interconnect)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 19:09
4	0	((((measur\$5 calculat\$4) near15 stress) near12 (cu copper metal metallization wiring interconnect)) and 700/121.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 18:40
5	40	((((measur\$5 calculat\$4) near15 stress) near12 (cu copper metal metallization wiring interconnect)) and 438/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 18:41
6	81	((measur\$5 calculat\$4) near15 stress) near12 (cu copper)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 19:11
7	70	((((measur\$5 calculat\$4) near15 stress) near12 (cu copper)) not (((measur\$5 calculat\$4) near15 stress) near12 (cu copper metal metallization wiring interconnect)) and 438/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 19:11
8	3	5175115.URPN.	USPAT	2004/05/13 19:21
9	38	(measur\$5 calculat\$4) near15 (((compressive tensile mechanical) adj stress) modulus) near15 (metallization interconnect wiring (metal adj (film layer)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 19:24
10	39	(measur\$5 calculat\$4) near15 (((compressive tensile mechanical) near3 stress) modulus) near15 (metallization interconnect wiring (metal adj (film layer)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 19:24
11	34	((measur\$5 calculat\$4) near15 (((compressive tensile mechanical) near3 stress) modulus) near15 (metallization interconnect wiring (metal adj (film layer))) ) not (((measur\$5 calculat\$4) near15 stress) near12 (cu copper metal metallization wiring interconnect)) and 438/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 19:24
12	34	((((measur\$5 calculat\$4) near15 (((compressive tensile mechanical) near3 stress) modulus) near15 (metallization interconnect wiring (metal adj (film layer))) ) not (((measur\$5 calculat\$4) near15 stress) near12 (cu copper metal metallization wiring interconnect)) and 438/\$.ccls.) not (((measur\$5 calculat\$4) near15 stress) near12 (cu copper metal metallization wiring interconnect)) and 438/\$.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 19:34

13	451	stress and ((cu copper) near2 (damascene inlai?))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 20:15
14	120	((mechanical tensile compressive) near3 stress) and ((cu copper) near2 (damascene inlai?))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 20:15
15	54	((((mechanical tensile compressive) near3 stress) and ((cu copper) near2 (damascene inlai?))) and @ad<20010613	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 20:16
16	26	((((mechanical tensile compressive) near3 stress) and ((cu copper) near2 (damascene inlai?))) and @rlad<20010613	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 20:16
17	73	(((((mechanical tensile compressive) near3 stress) and ((cu copper) near2 (damascene inlai?))) and @ad<20010613) (((mechanical tensile compressive) near3 stress) and ((cu copper) near2 (damascene inlai?))) and @rlad<20010613)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/13 20:16